

Notice of References Cited	Application/Control No. 10/020,911	Applicant(s)/Patent Under Reexamination VANDENTOP ET AL.	
	Examiner David A. Zarneke	Art Unit 2827	Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-			
	B	US-			
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FOREIGN PATENT DOCUMENTS

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NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
*	U	FAN, A. et al., "Copper Wafer Bonding," Electrochemical and Solid-state Letters. 2(10) 534-536 (1999)
	V	
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	X	

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
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